

PCN # 1776A

DATE: August 20, 2019

EXPECTED PCN SHIP DATE: August 20, 2019



Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE

PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

<input type="checkbox"/> DESIGN	<input type="checkbox"/> WAFER FAB	<input checked="" type="checkbox"/> ASSEMBLY	<input type="checkbox"/> TEST	<input type="checkbox"/> ELEC/MECH SPECS
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AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: -

Products: MAX16543/45, MAX16550,
MAX20710/30/31/34/35/43, VT505

Current Assembler for products in Flip Chip QFN (FCQFN)
package using 1P1M bump process (One layer of
Polyimide/Metal)

CHANGE TO: -

Products using 2P2M bump process (Two layers of
Polyimide/Metal) will be assembled at UTAC THAI LIMITED /
THAILAND (UTL)

JUSTIFICATION: The 2P2M bump process change is required improve the quality and reliability of Maxim's Flip chip QFN package. Maxim has qualified UTL to perform final assembly using the new bump process flow.

Related qualification reports and results are attached (ref. R40238)

There are no changes to the form, fit or function of the devices.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative

or

Nasser AliChaouche, PCN Coordinator

408-601-5660 / pcn.coordinator@maximintegrated.com